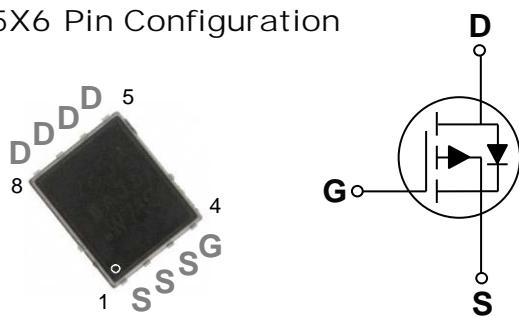


30V P-Channel MOSFETs

General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

PPAK5X6 Pin Configuration



BVDSS	RDS(ON)	ID
-30V	4.5mΩ	-90A

Features

- -30V, -90A, RDS(ON) = 4.5mΩ @ VGS = -10V
- Fast switching
- Green Device Available
- Suit for -4.5V Gate Drive Applications

Applications

- Motor Driver Applications
- POL Applications
- Load Switch
- LED Application

Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	-30	V
VGS	Gate-Source Voltage	± 20	V
I _D	Drain Current – Continuous (Tc=25 °C)	-90	A
	Drain Current – Continuous (Tc=100 °C)	-56	A
I _{DM}	Drain Current – Pulsed ¹	-360	A
P _D	Power Dissipation (Tc=25 °C)	136	W
	Power Dissipation – Derate above 25 °C	1.08	W/°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction to Ambient	---	62	°C/W
R _{θJC}	Thermal Resistance Junction to Case	---	0.92	°C/W



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30V P-Channel MOSFETs

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=-250\mu\text{A}$	-30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_{\text{D}}=-1\text{mA}$	---	-0.03	---	$\text{V}/^\circ\text{C}$
$I_{\text{DS}}^{\text{SS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-30\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	-1	μA
		$V_{\text{DS}}=-24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	-10	μA
$I_{\text{GS}}^{\text{SS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA

On Characteristics

$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=-10\text{V}$, $I_{\text{D}}=-30\text{A}$	---	3.5	4.5	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$, $I_{\text{D}}=-20\text{A}$	---	5	7	$\text{m}\Omega$
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_{\text{D}}=-250\mu\text{A}$	-1.2	-1.6	-2.2	V
			---	4	---	$\text{mV}/^\circ\text{C}$
g_{fs}	Forward Transconductance	$V_{\text{DS}}=-10\text{V}$, $I_{\text{D}}=-5\text{A}$	---	25	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge ^{2,3}	$V_{\text{DS}}=-15\text{V}$, $V_{\text{GS}}=-10\text{V}$, $I_{\text{D}}=-10\text{A}$	---	108	150	nC
Q_{gs}	Gate-Source Charge ^{2,3}		---	15	25	
Q_{gd}	Gate-Drain Charge ^{2,3}		---	17.4	30	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time ^{2,3}	$V_{\text{DD}}=-15\text{V}$, $V_{\text{GS}}=-10\text{V}$, $R_{\text{G}}=6\Omega$	---	28	56	ns
T_r	Rise Time ^{2,3}		---	16	32	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time ^{2,3}		---	178	340	
T_f	Fall Time ^{2,3}		---	72	140	
C_{iss}	Input Capacitance	$V_{\text{DS}}=-25\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$	---	6220	9000	pF
C_{oss}	Output Capacitance		---	782	1100	
C_{rss}	Reverse Transfer Capacitance		---	412	600	

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	-85	A
			---	---	-170	A
V_{SD}	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{s}}=-1\text{A}$, $T_J=25^\circ\text{C}$	---	---	-1	V
t_{rr}	Reverse Recovery Time	$V_{\text{GS}}=0\text{V}$, $I_{\text{s}}=-30\text{A}$, $\text{di}/\text{dt}=100\text{A}/\mu\text{s}$	---	63.8	---	ns
Q_{rr}	Reverse Recovery Charge	$T_J=25^\circ\text{C}$	---	62.3	---	nC

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

30V P-Channel MOSFETs

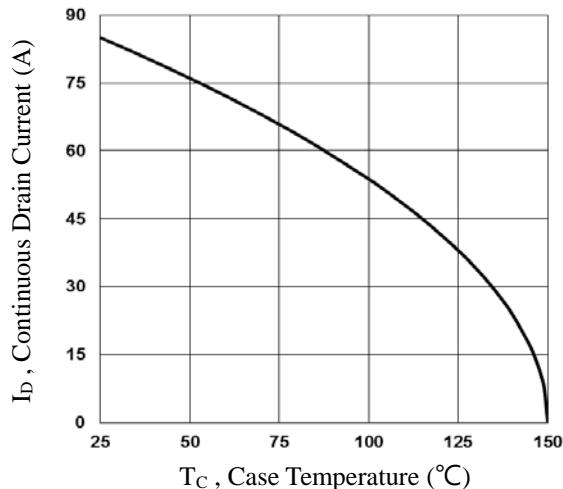


Fig.1 Continuous Drain Current vs. T_C

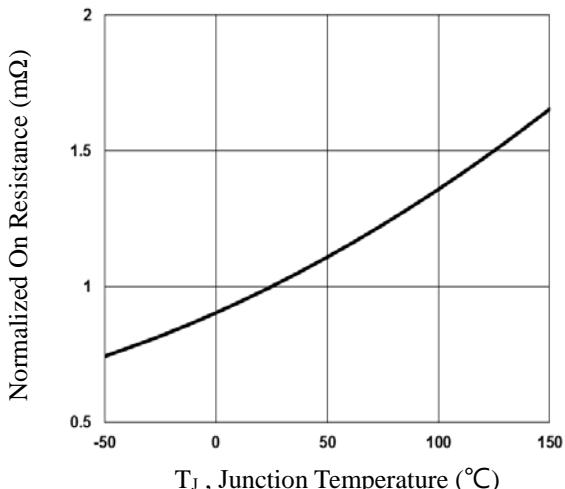


Fig.2 Normalized RDS(on) vs. T_J

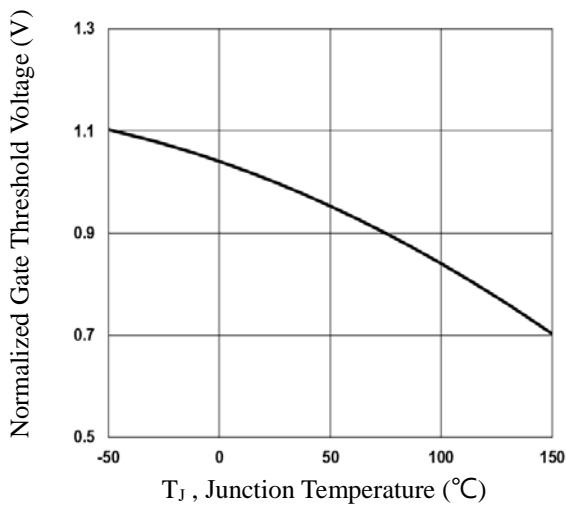


Fig.3 Normalized V_{th} vs. T_J

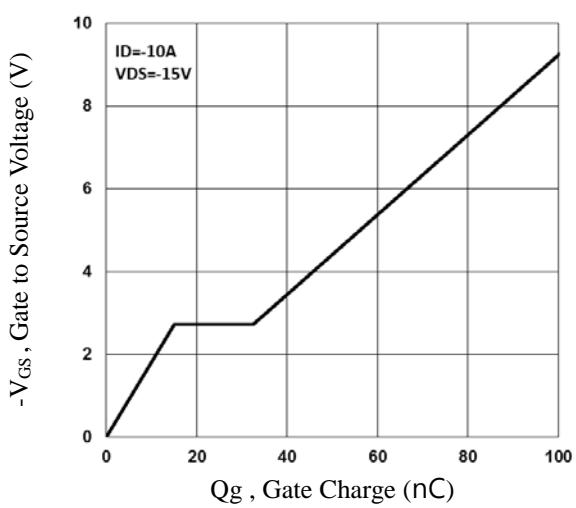


Fig.4 Gate Charge Waveform

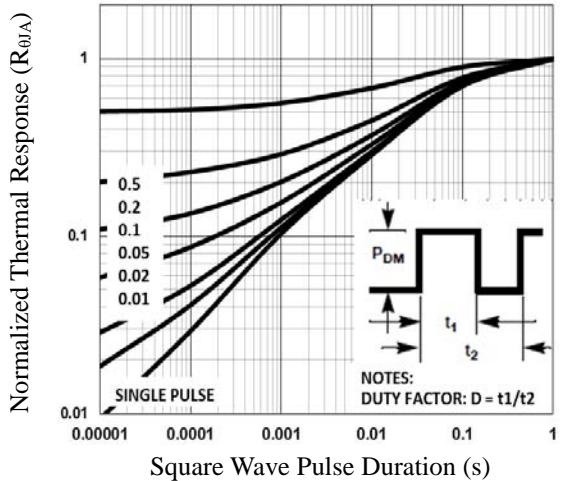


Fig.5 Normalized Transient Impedance

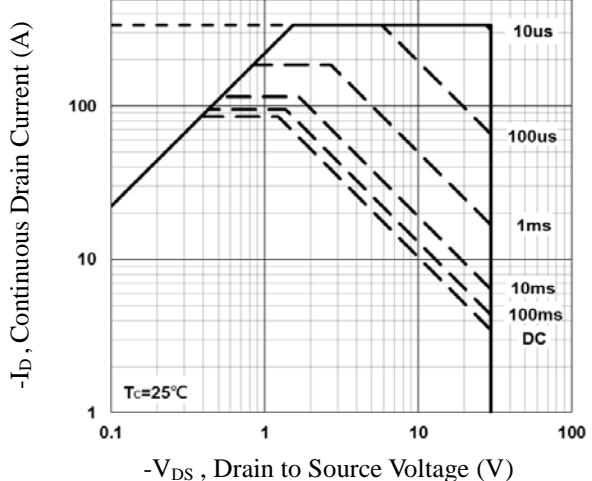


Fig.6 Maximum Safe Operation Area

30V P-Channel MOSFETs

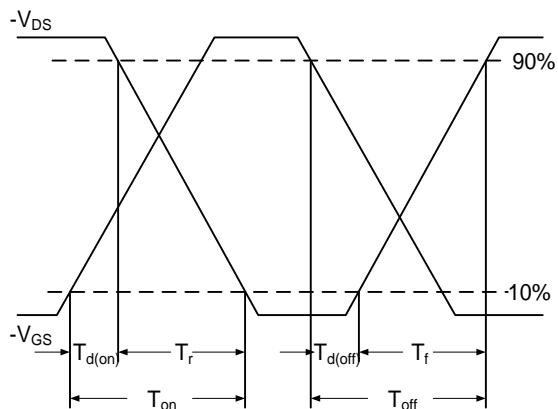


Fig.7 Switching Time Waveform

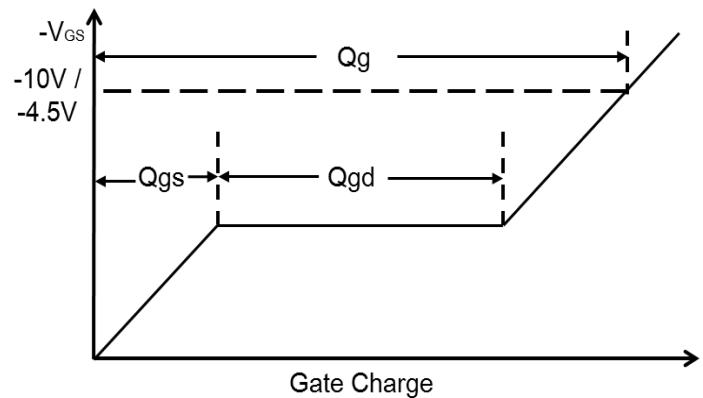
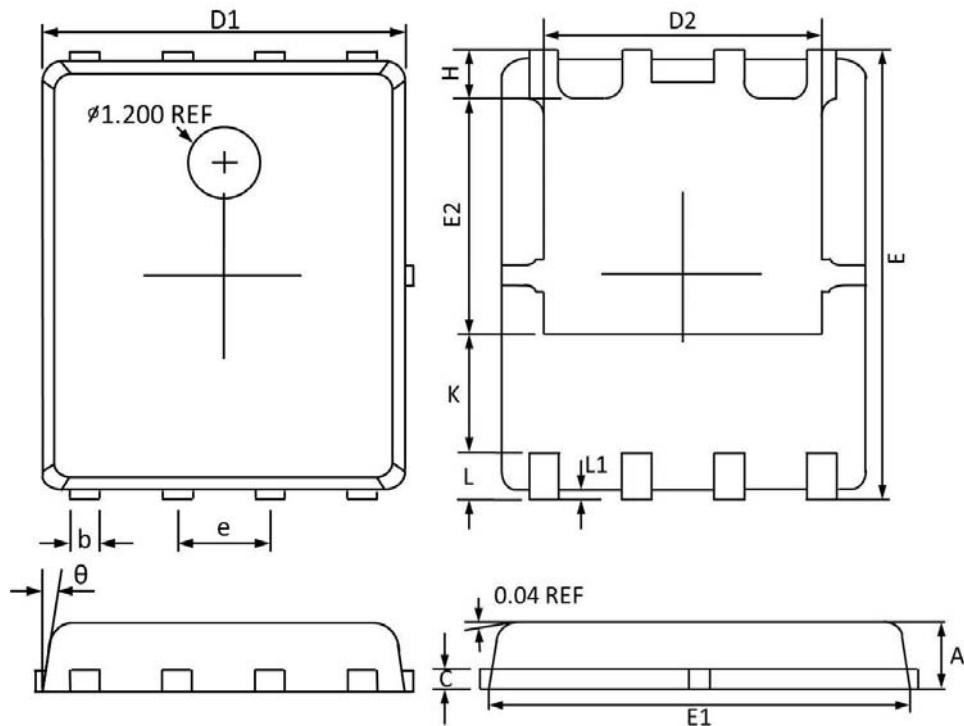


Fig.8 Gate Charge Waveform

30V P-Channel MOSFETs

PPAK5x6 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.100	0.800	0.043	0.031
b	0.510	0.330	0.020	0.013
C	0.300	0.200	0.012	0.008
D1	5.100	4.800	0.201	0.189
D2	4.100	3.610	0.161	0.142
E	6.200	5.900	0.244	0.232
E1	5.900	5.700	0.232	0.224
E2	3.780	3.350	0.149	0.132
e	1.27BSC		0.05BSC	
H	0.700	0.410	0.028	0.016
K	1.500	1.100	0.059	0.043
L	0.710	0.510	0.028	0.020
L1	0.200	0.060	0.008	0.002
θ	12°	0°	12°	0°